

FIG. 1

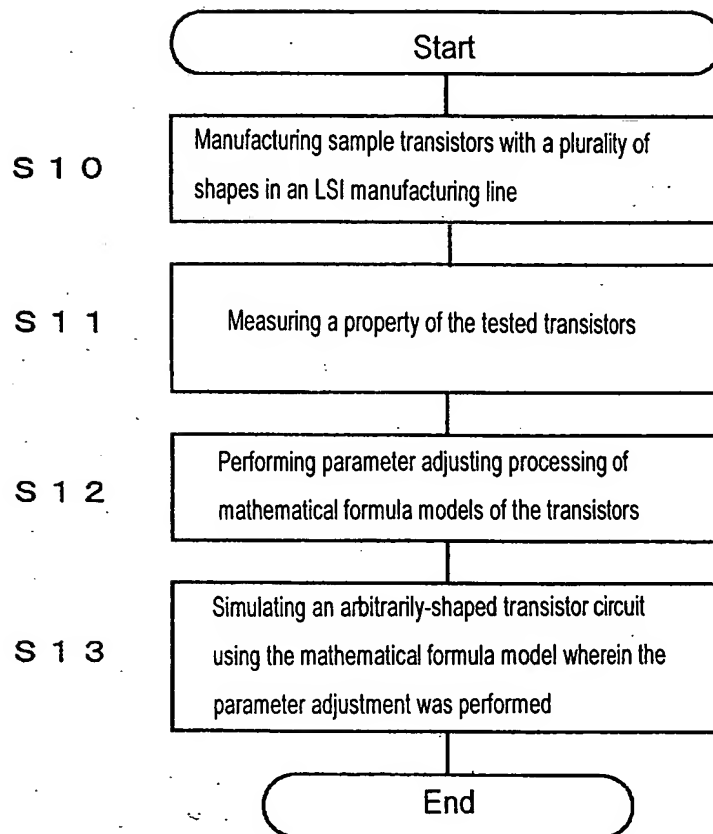


FIG. 2

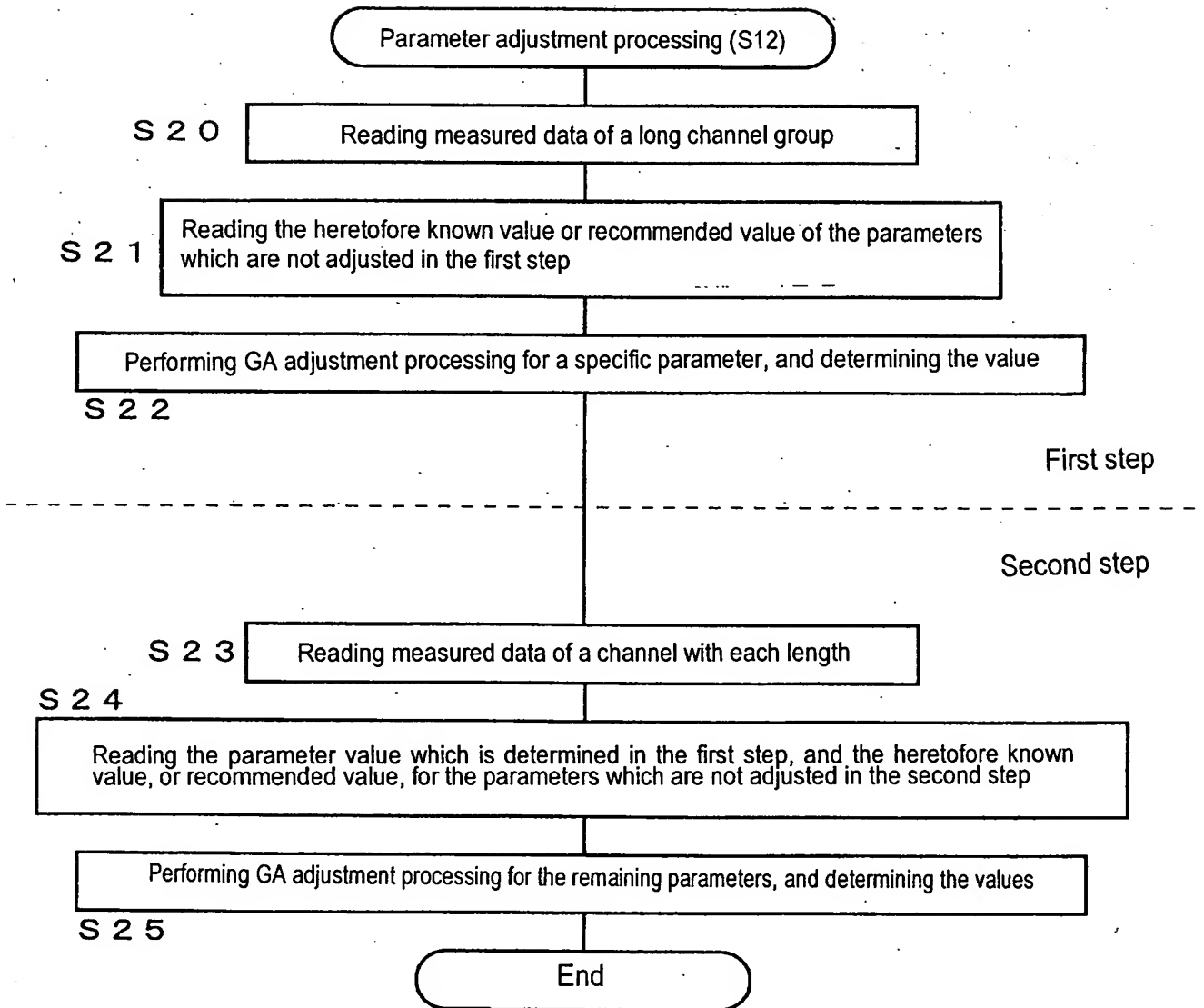


FIG. 3

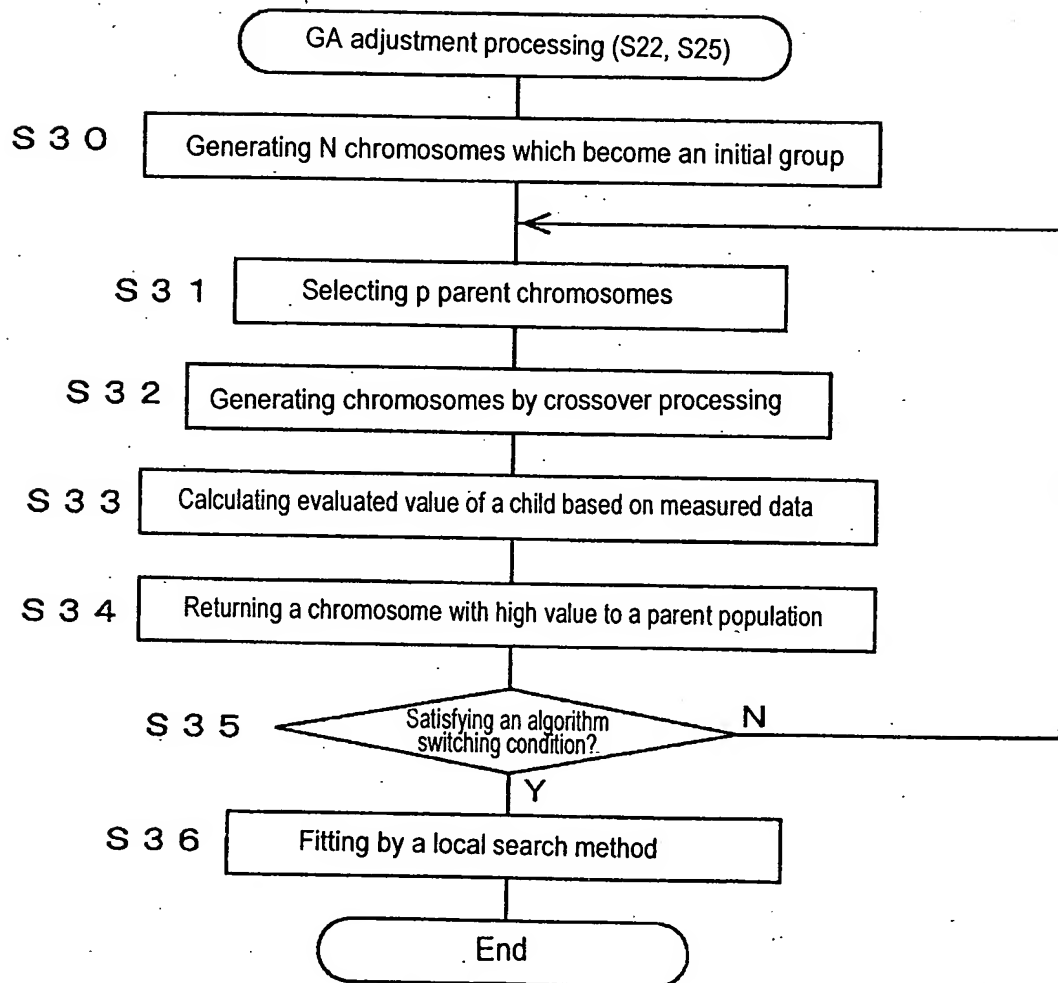


FIG. 4

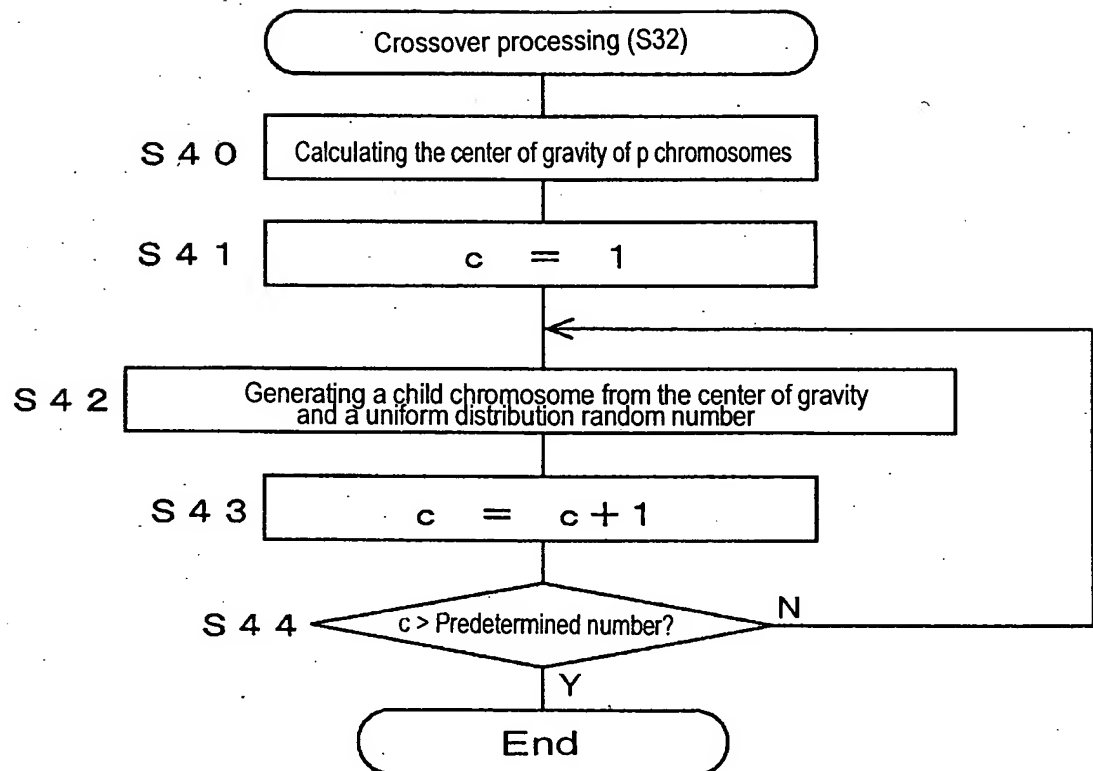


FIG. 5

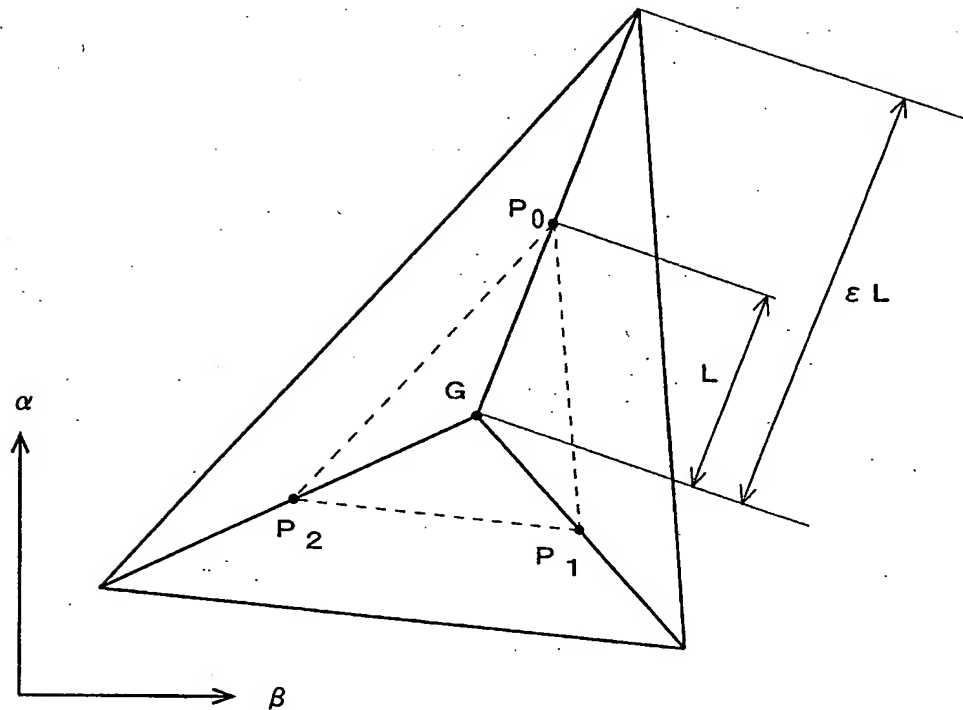


FIG. 6

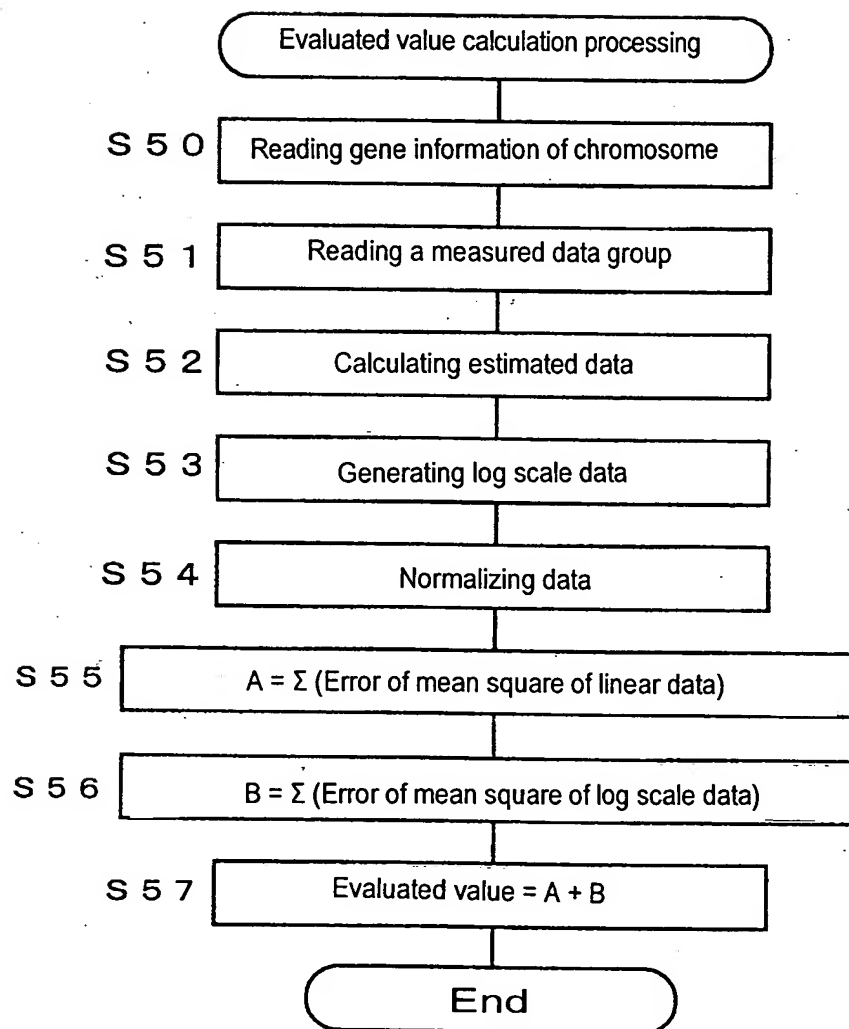


FIG. 7

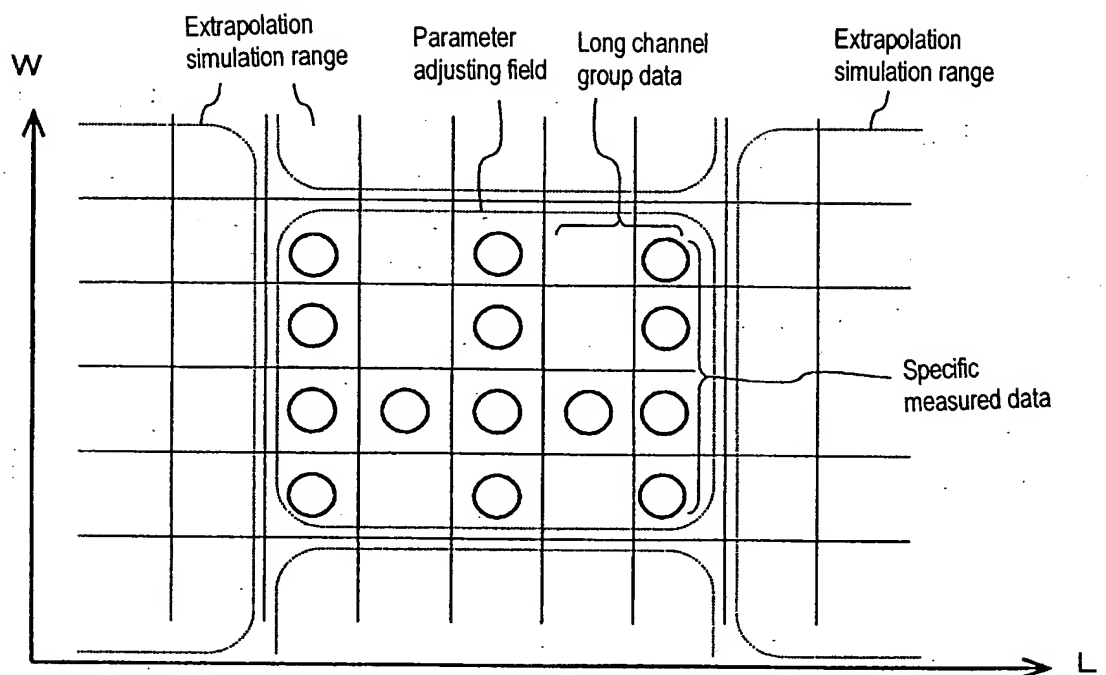


FIG. 8 (a)

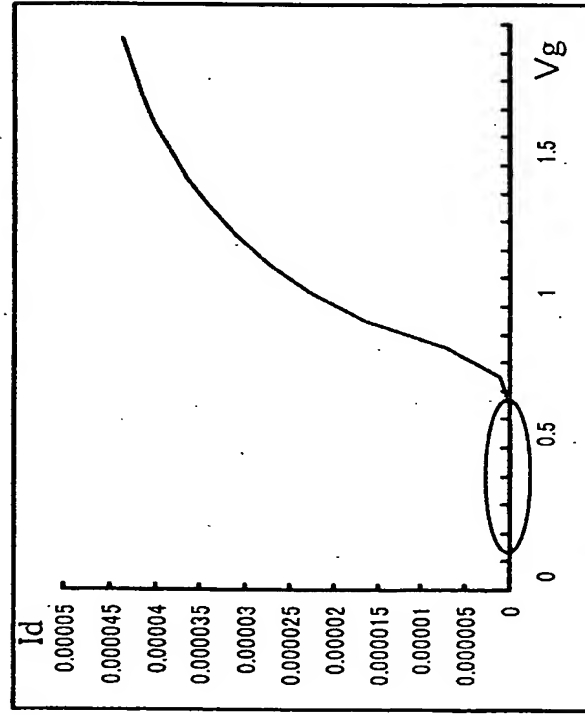


FIG. 8 (b)

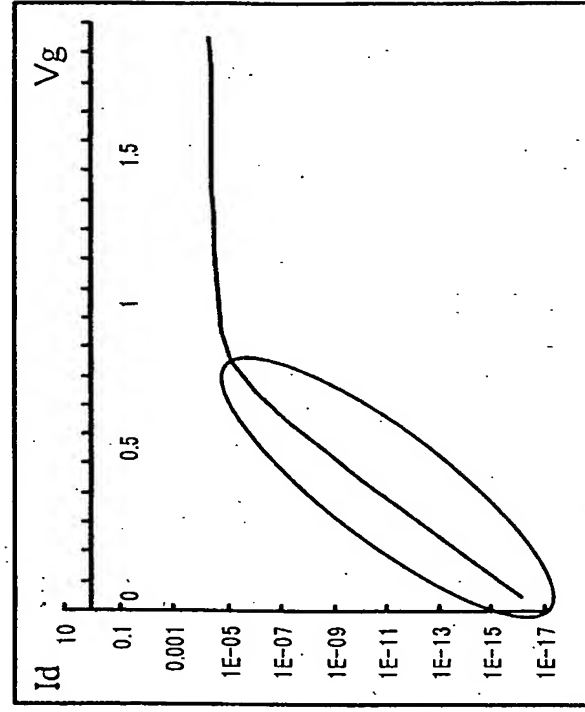


FIG. 9

Technological Parameters		
TOX	oxide thickness	m
XLD	gate-overlap length	m
XWD	gate-overlap width	m
XPOLYD	difference between gate-poly and design lengths	m
TPOLY	height of the gate poly-Si	m
RS	source-contact resistance	VA-1m
RD	drain-contact resistance	VA-1m
●NSUBC	substrate-impurity concentration	cm-3
●NSUBP	maximum pocket concentration	cm-3
●VFBC	flat-band voltage	V
LP	pocket penetration length	m
XQY	distance from drain junction to maximum electric field point	m

FIG. 10

Mobility		
VDS0	drain voltage for extracting the low-field mobility	V
●MUECB0	Coulomb scattering	cm ² V ⁻¹ S ⁻¹
●MUECB1	Coulomb scattering	cm ² V ⁻¹ S ⁻¹
MUEPH0	phonon scattering	cm ² (Vs) ⁻¹ (V cm ⁻¹) ^{MUEPH1}
●MUEPH1	phonon scattering	—
MUETMP	temperature dependence of phonon scattering	—
MUESR0	surface-roughness scattering	cm ² (V s) ⁻¹ (V cm ⁻¹) ^{MUESR1}
●MUESR1	surface-roughness scattering	—
NDEP	coefficient of effective-electric field	—
NINV	coefficient of effective-electric field	—
NINVD	modification of NINV	V ⁻¹
BB	high-field-mobility degradation	—
●VMAX	maximum saturation velocity	cm s ⁻¹
VOVER	velocity overshoot effect	cmVOVERP
VOVERP	L _{gate} dependence of velocity overshoot	—
RPOCK1	resistance coefficient caused by the potential barrier	V ² A-RPOCP1μm ¹ -RPOCP2
RPOCK2	resistance coefficient caused by the potential barrier	V
RPOCP1	resistance coefficient caused by the potential barrier	—
RPOCP2	resistance coefficient caused by the potential barrier	—